MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

Complementary Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Straight Lead Version in Plastic Sleeves (“1” Suffix)
- Lead Formed Version in 16 mm Tape and Reel (“T4” Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Epoxy Meets UL 94, V−0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V
  Machine Model, C > 400 V
- Pb−Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector−Emitter Voltage MJD31, MJD32 MJD31C, MJD32C	V_{CEO}	 40 100	Vdc
Collector−Base Voltage MJD31, MJD32 MJD31C, MJD32C	V_{CB}	 40 100	Vdc
Emitter−Base Voltage	V_{EB}	5	Vdc
Collector Current − Continuous − Peak	I_C	3 5	Adc
Base Current	I_B	1	Adc
Total Power Dissipation @ T_C = 25°C Derate above 25°C	P_D	15 0.12	W W/°C
Total Power Dissipation @ T_A = 25°C Derate above 25°C	P_D	1.56 0.012	W W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	8.3	°C/W
Thermal Resistance, Junction−to−Ambient*	$R_{\theta JA}$	80	°C/W
Lead Temperature for Soldering Purposes	T_L	260	°C

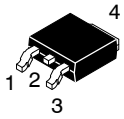
*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ON Semiconductor®

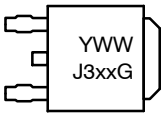
http://onsemi.com

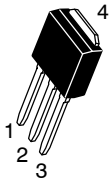
SILICON
POWER TRANSISTORS
3 AMPERES
40 AND 100 VOLTS
15 WATTS

MARKING DIAGRAMS

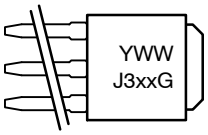


DPAK
CASE 369C
STYLE 1





DPAK−3
CASE 369D
STYLE 1



Y	= Year
WW	= Work Week
xx	= 1, 1C, 2, or 2C
G	= Pb−Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector−Emitter Sustaining Voltage (Note 1) (I_C = 30 mAdc, I_B = 0)	MJD31, MJD32 MJD31C, MJD32C	$V_{CEO(sus)}$	 40 100	 − −	Vdc
Collector Cutoff Current (V_{CE} = 40 Vdc, I_B = 0) (V_{CE} = 60 Vdc, I_B = 0)	 MJD31, MJD32 MJD31C, MJD32C	I_{CEO}	−	50	μAdc
Collector Cutoff Current (V_{CE} = Rated V_{CEO}, V_{EB} = 0)		ICES	−	20	μAdc
Emitter Cutoff Current (V_{BE} = 5 Vdc, I_C = 0)		I_{EBO}	−	1	mAdc
ON CHARACTERISTICS (Note 1)					
DC Current Gain (I_C = 1 Adc, V_{CE} = 4 Vdc) (I_C = 3 Adc, V_{CE} = 4 Vdc)		h_{FE}	 25 10	 − 50	−
Collector−Emitter Saturation Voltage (I_C = 3 Adc, I_B = 375 mAdc)		$V_{CE(sat)}$	−	1.2	Vdc
Base−Emitter On Voltage (I_C = 3 Adc, V_{CE} = 4 Vdc)		$V_{BE(on)}$	−	1.8	Vdc
DYNAMIC CHARACTERISTICS					
Current Gain − Bandwidth Product (Note 2) (I_C = 500 mAdc, V_{CE} = 10 Vdc, f_{test} = 1 MHz)		f_T	3	−	MHz
Small−Signal Current Gain (I_C = 0.5 Adc, V_{CE} = 10 Vdc, f = 1 kHz)		h_{fe}	20	−	−

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
2. $f_T = |h_{fe}| \cdot f_{test}$.

TYPICAL CHARACTERISTICS

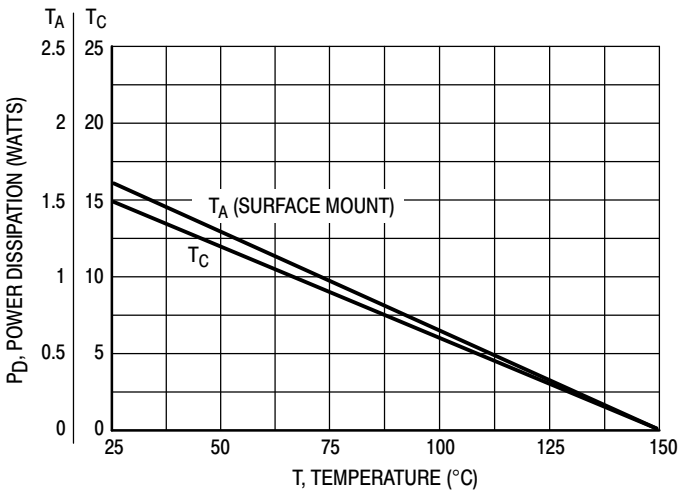
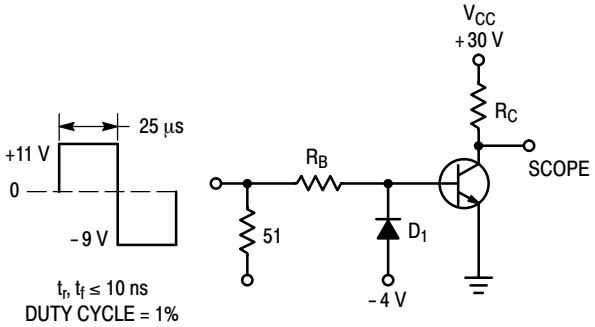


Figure 1. Power Derating



R_B and R_C VARIED TO OBTAIN DESIRED CURRENT LEVELS
D_1 MUST BE FAST RECOVERY TYPE, e.g.:
1N5825 USED ABOVE $I_B \approx 100$ mA
MSD6100 USED BELOW $I_B \approx 100$ mA
REVERSE ALL POLARITIES FOR PNP.

Figure 2. Switching Time Test Circuit

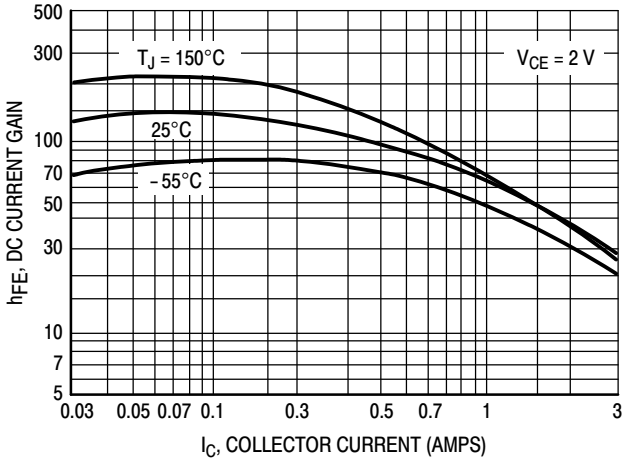


Figure 3. DC Current Gain

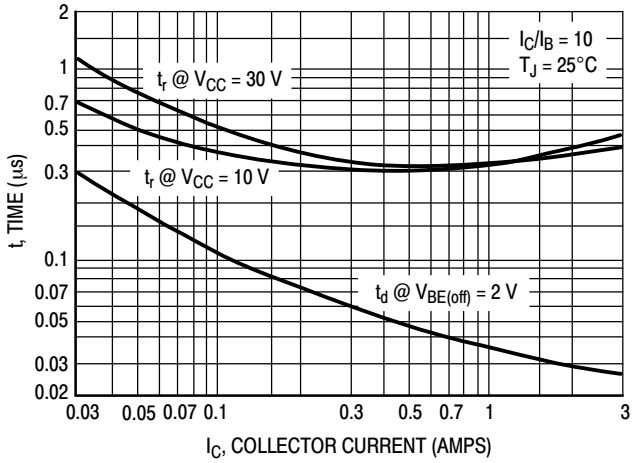


Figure 4. Turn−On Time

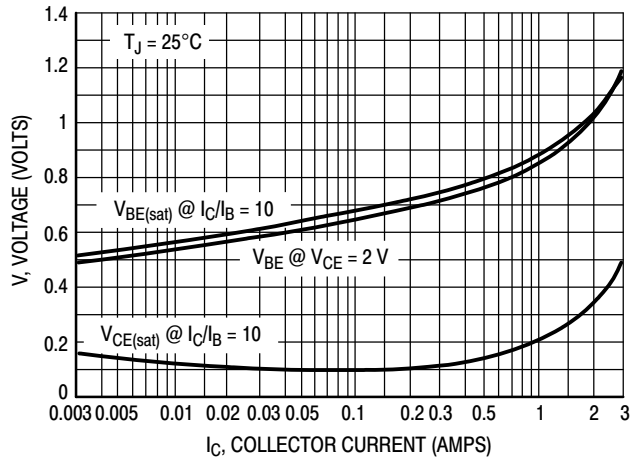


Figure 5. “On” Voltages

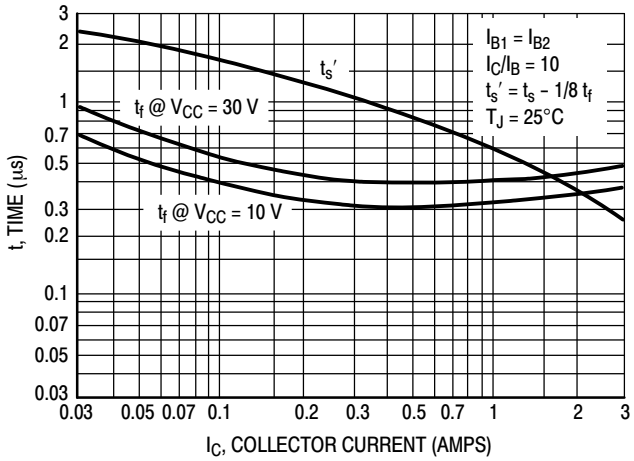


Figure 6. Turn−Off Time

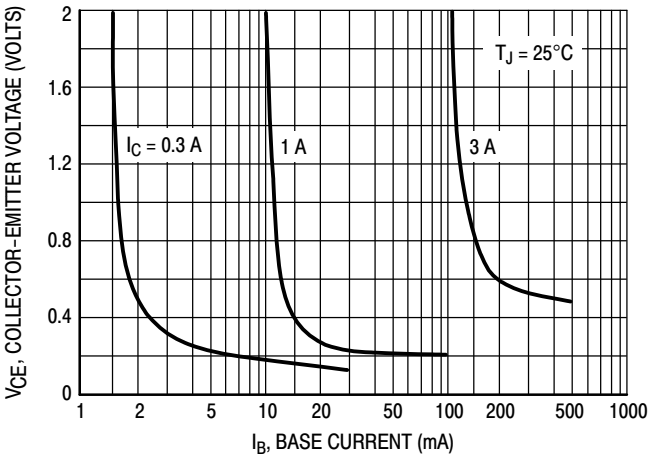


Figure 7. Collector Saturation Region

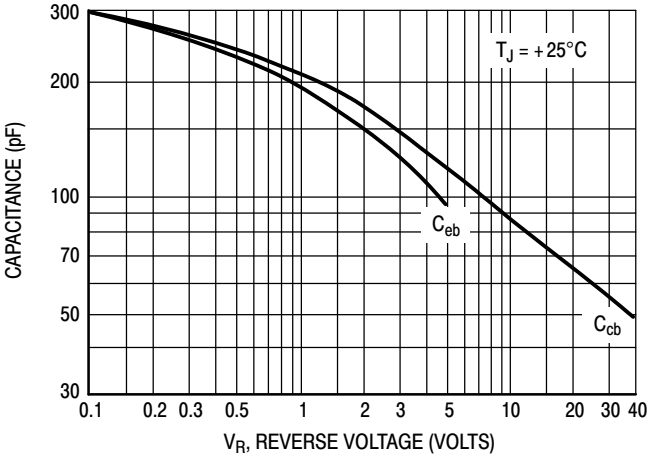


Figure 8. Capacitance

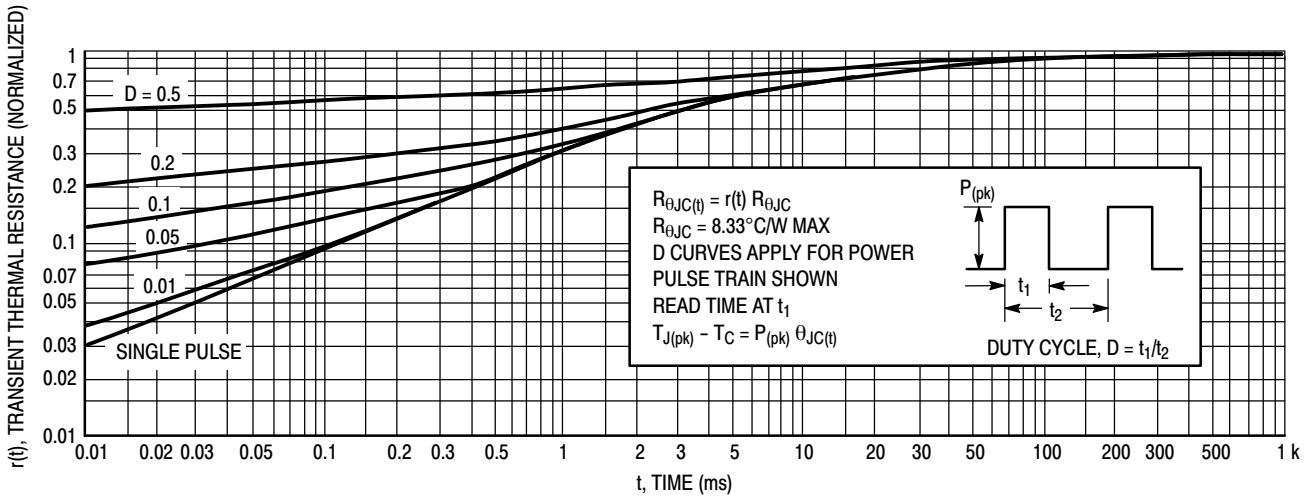


Figure 9. Thermal Response

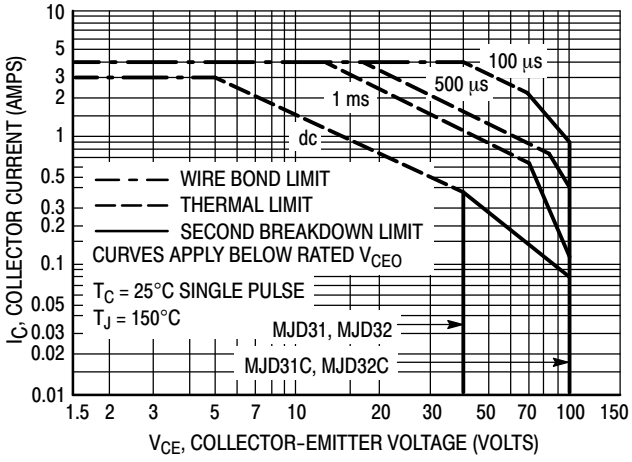


Figure 10. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 10 is based on $T_{J(pk)}$ = 150°C; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150°C$. $T_{J(pk)}$ may be calculated from the data in Figure 9. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

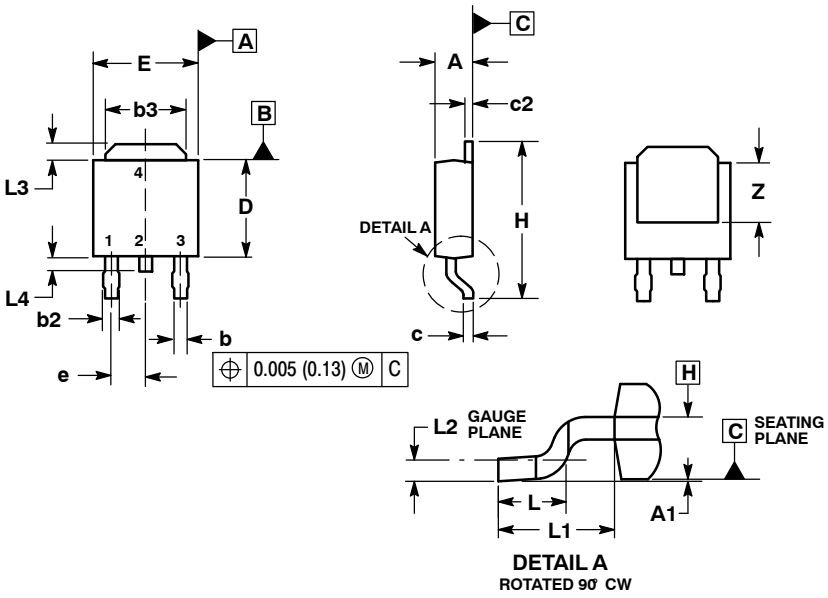
ORDERING INFORMATION

Device	Package Type	Package	Shipping†
MJD31C	DPAK	369C	75 Units / Rail
MJD31CG	DPAK (Pb−Free)	369C	75 Units / Rail
MJD31C1	DPAK−3	369D	75 Units / Rail
MJD31C1G	DPAK−3 (Pb−Free)	369D	75 Units / Rail
MJD31CRL	DPAK	369C	1800 Tape & Reel
MJD31CRLG	DPAK (Pb−Free)	369C	1800 Tape & Reel
MJD31CT4	DPAK	369C	2500 Tape & Reel
MJD31CT4G	DPAK (Pb−Free)	369C	2500 Tape & Reel
MJD31T4	DPAK	369C	2500 Tape & Reel
MJD31T4G	DPAK (Pb−Free)	369C	2500 Tape & Reel
MJD32C	DPAK	369C	75 Units / Rail
MJD32CG	DPAK (Pb−Free)	369C	75 Units / Rail
MJD32C1	DPAK−3	369D	75 Units / Rail
MJD32C1G	DPAK−3 (Pb−Free)	369D	75 Units / Rail
MJD32CRL	DPAK	369C	1800 Tape & Reel
MJD32CRLG	DPAK (Pb−Free)	369C	1800 Tape & Reel
MJD32CT4	DPAK	369C	2500 Tape & Reel
MJD32CT4G	DPAK (Pb−Free)	369C	2500 Tape & Reel
MJD32RL	DPAK	369C	1800 Tape & Reel
MJD32RLG	DPAK (Pb−Free)	369C	1800 Tape & Reel
MJD32T4	DPAK	369C	2500 Tape & Reel
MJD32T4G	DPAK (Pb−Free)	369C	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK
CASE 369C−01
ISSUE D

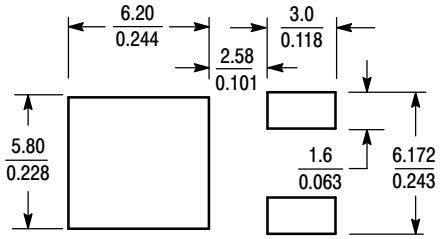


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	−−−	0.040	−−−	1.01
Z	0.155	−−−	3.93	−−−

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

SOLDERING FOOTPRINT*

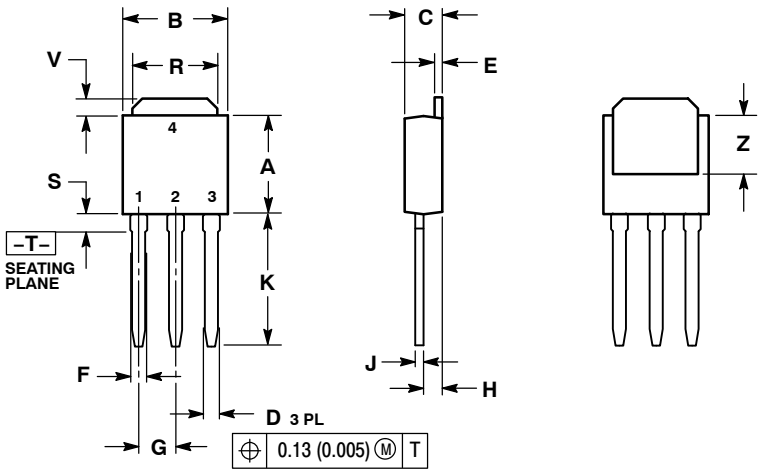


SCALE 3:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

DPAK−3
CASE 369D−01
ISSUE B



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	−−−	3.93	−−−

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5773−3850

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

MJD31/D